

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|--------|---|---|------------------|---------|------------------|
| L1 | 137684 | (multilayer (multi adj layer) ((metal conductor) with (insulation insulated insulating))) with (carrier body substrate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/25 12:48 |
| L2 | 521791 | (reinforce reinforcing reinforcement reinforced metal) with (sheet) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/25 12:53 |
| L3 | 4627 | 1 same 2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/25 12:49 |
| L4 | 717 | (semiconductor die chip dice ic (integrated adj circuit)) same 3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/25 12:53 |
| L5 | 56 | (bump ball bga) same 4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/25 12:53 |
| L6 | 590482 | (reinforce reinforcing reinforcement reinforced metal) with (foil sheet) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/25 12:53 |
| L7 | 6889 | 1 same 6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/25 12:53 |
| L8 | 1130 | (semiconductor die chip dice ic (integrated adj circuit)) same 7 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/25 12:53 |

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|----|----|------------------------|---|----|----|------------------|
| L9 | 92 | (bump ball bga) same 8 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/25 12:53 |
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